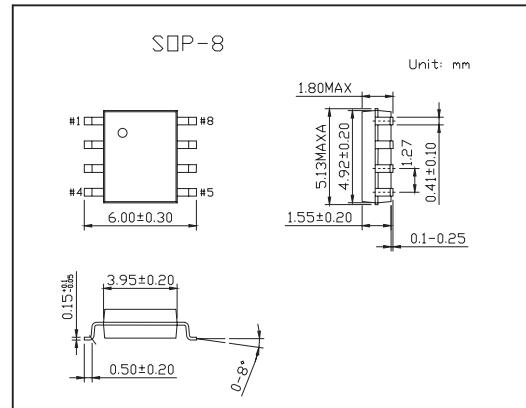
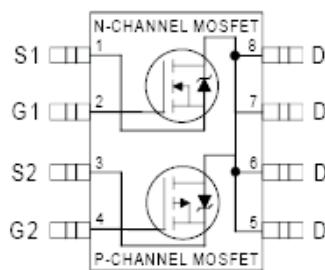


■ Features

- Generation V Technology
- Ultra Low On-Resistance
- Complimentary Half Bridge
- Surface Mount
- Fully Avalanche Rated



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}	30	-30	V
Continuous Drain Current, V _{GS} @ 10V @ T _a = 25°C	I _D	5.8	-4.3	
Continuous Drain Current, V _{GS} @ 10V @ T _a = 70°C	I _D	4.6	-3.4	A
Pulsed Drain Current *1	I _{DM}	46	-34	
Power Dissipation @T _a = 25°C	P _D	2.5		W
Linear Derating Factor		0.02		W/°C
Gate-to-Source Voltage	V _{GS}	±20		V
Peak Diode Recovery dv/dt *2	dv/dt	5.0	-5.0	V/ns
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to + 150		°C
Maximum Junction-to-Ambient *3	R _{θ JA}	50		°C/W

*1 Repetitive rating; pulse width limited by max. junction temperature.

*2 N-Channel I_{SD} ≤ 2.4A, di/dt ≤ 73A/μ s, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

P-Channel I_{SD} ≤ -1.8A, di/dt ≤ 90A/μ s, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

*3 Surface mounted on FR-4 board, t ≤ 10sec.

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons			Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	V(BR)DSS	V _{GS} = 0V, I _D = 250 μA	N-Ch	30				V
		V _{GS} = 0V, I _D = 250 μA	P-Ch	-30				
Breakdown Voltage Temp. Coefficient	△V(BR)DSS/△T _J	I _D = 1mA, Reference to 25°C	N-Ch		0.032			V/°C
		I _D = 1mA, Reference to 25°C	P-Ch		-0.037			
Static Drain-to-Source On-Resistance	R _{DSS(on)}	V _{GS} = 10V, I _D = 5.8A*1	N-Ch		0.038	0.045		Ω
		V _{GS} = 4.5V, I _D = 4.9A*1	N-Ch		0.055	0.075		
Static Drain-to-Source On-Resistance	R _{DSS(on)}	V _{GS} = -10V, I _D = -4.3A*1	P-Ch		0.070	0.090		Ω
		V _{GS} = -4.5V, I _D = -3.7A*1	P-Ch		0.130	0.180		
Gate Threshold Voltage	V _{GSS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	N-Ch	1.0				V
		V _{DS} = V _{GS} , I _D = -250 μA	P-Ch	-1.0				
Forward Transconductance	g _{fs}	V _{DS} = 15V, I _D = 2.4A*1	N-Ch	5.2				S
		V _{DS} = -24V, I _D = -1.8A*1	P-Ch	2.5				
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V	N-Ch			1.0		μA
		V _{DS} = -24V, V _{GS} = 0V	P-Ch			-1.0		
		V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C	N-Ch			25		
		V _{DS} = -24V, V _{GS} = 0V, T _J = 125°C	P-Ch			-25		
Gate-to-Source Forward Leakage	I _{GSS}	V _{GS} = ±20V	N-Ch			±100		
			P-Ch			±100		
Total Gate Charge	Q _g	N-Channel I _D = 2.4A, V _{DS} = 24V, V _{GS} = 10V P-Channel I _D = -1.8A, V _{DS} = -24V, V _{GS} = -10V	N-Ch			25		nC
Gate-to-Source Charge	Q _{gs}		P-Ch			25		
Gate-to-Drain ("Miller") Charge	Q _{gd}		N-Ch			2.9		
			P-Ch			2.9		
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 15V, I _D = 2.4A, R _G = 6.0 Ω P-Channel R _D = 6.2 Ω V _{DD} = -15V, I _D = -1.8A, R _G = 6.0 Ω R _D = 8.2 Ω	N-Ch			6.8		ns
Rise Time	t _r		P-Ch			11		
Turn-Off Delay Time	t _{d(off)}		N-Ch			21		
Fall Time	t _f		P-Ch			17		
Internal Drain Inductance	L _D	Between lead, 6mm (0.25in.) from package and center of die contact	N-Ch			22		nH
Internal Source Inductance	L _S		P-Ch			25		
Input Capacitance	C _{iss}		N-Ch			7.7		
Output Capacitance	C _{oss}		P-Ch			18		
Reverse Transfer Capacitance	C _{rss}	N-Channel V _{GS} = 0V, V _{DS} = 25V, f = 1.0MHz P-Channel V _{GS} = 0V, V _{DS} = -25V, f = 1.0MHz	N-Ch			4.0		pF
			P-Ch			4.0		
			N-Ch			6.0		
			P-Ch			6.0		

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	Is		N-Ch		3.1	A
			P-Ch		-3.1	
Pulsed Source Current (Body Diode) *2			N-Ch		46	
Diode Forward Voltage			P-Ch		-34	
Reverse Recovery Time	trr	TJ = 25°C, Is = 1.8A, VGS = 0V*1	N-Ch		1.0	V
		TJ = 25°C, Is = -1.8A, VGS = 0V*1	P-Ch		-1.0	
Reverse RecoveryCharge	Qrr	N-Channel TJ = 25°C, If = 2.4A, di/dt = 100A/μ s*1	N-Ch	47	71	ns
		P-Channel TJ=25°C, If=-1.8A,di/dt=-100A/ μ s*1	P-Ch	53	80	
			N-Ch	56	84	nC
			P-Ch	66	99	

*1 Pulse width ≤ 300 μ s; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited by max. junction temperature.